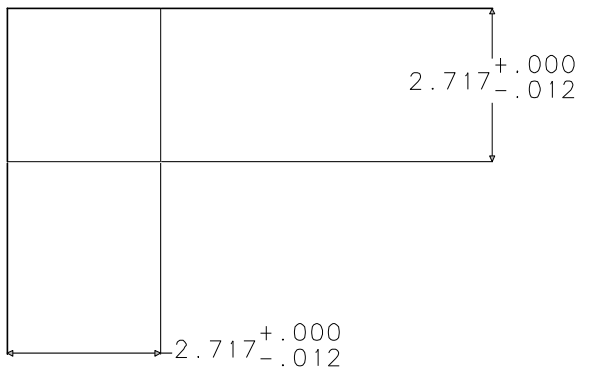

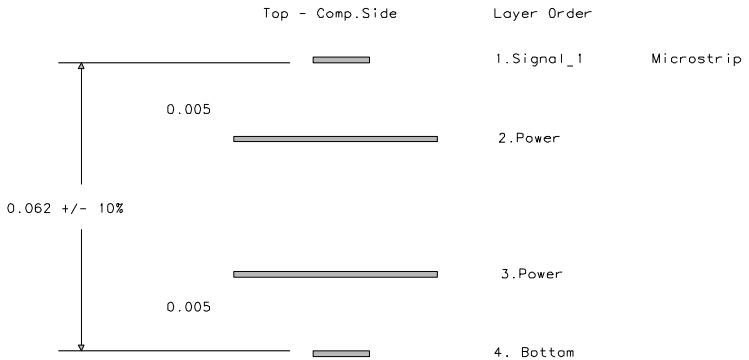

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.013	10	YES	---	
⊞	.014	270	YES	---	
⌀	.032	20	YES	---	
⊟	.041	10	YES	---	
⊖	.094	1	NO	---	
◫	.106	4	NO	---	

Board Characteristics - 4 LAYER BOARD

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4 , Tg > 170 C.
2. Minimum trace width and clearence: 0.006"
3. Impedance control: 50 Ohm for all 6 mil signal traces
4. 1 oz copper for all layers.
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Apply Solder Mask over bare copper.
8. Silkscreen on Component and Solder Sides.
10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS	DATE
DRAWN M.Bogdan	2/15/2011
CHECKED M.Bogdan	2/15/2011
ISSUED	

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE: PSEC3 - QFP Mezzanine Specification Drawing

SIZE | FSCM NO. | DWG.NO. 2726 | REV. A

SCALE 1/2 | SHEET

THIS SHEET IS COMPUTER GENERATED